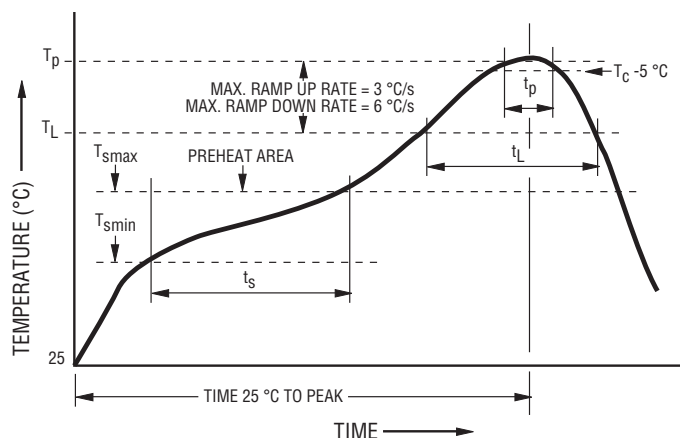
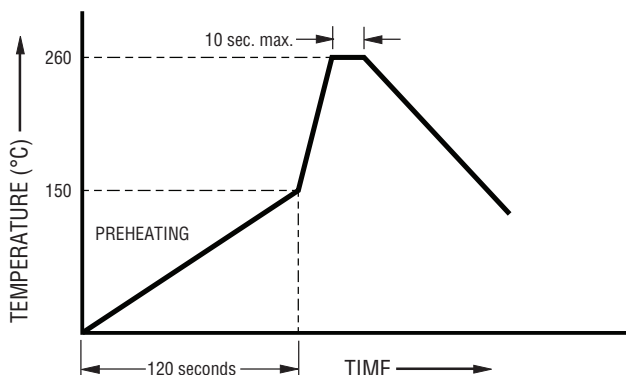


Solder Reflow Recommendations

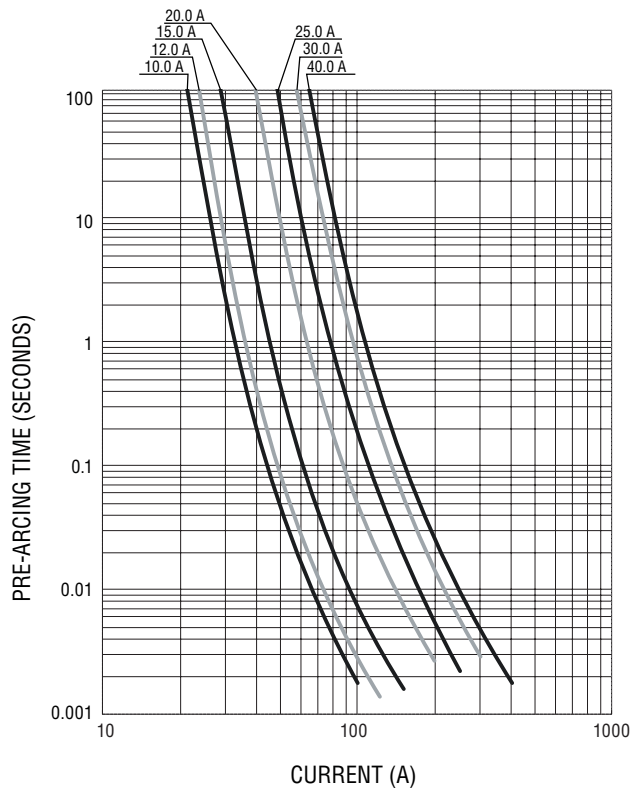
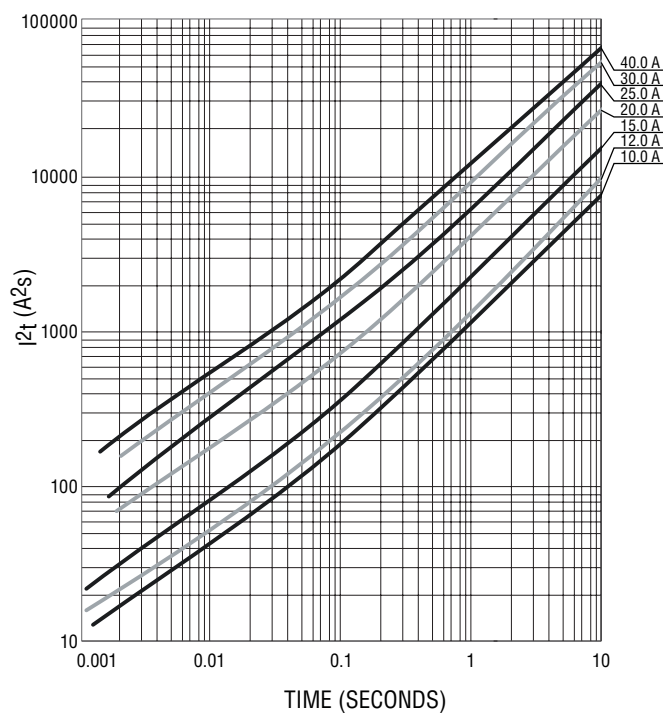
Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	150 °C 200 °C 60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	217 °C 60~150 seconds
Peak Package Body Temperature (T_p)	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_C)	30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Recommended Temperature Profile for Wave Soldering

Wave soldering is suitable for 1206 size models.

Average Pre-Arcing Time vs. Current Curves

Average I^2t vs. t Curves

REV. A 06/18

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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